



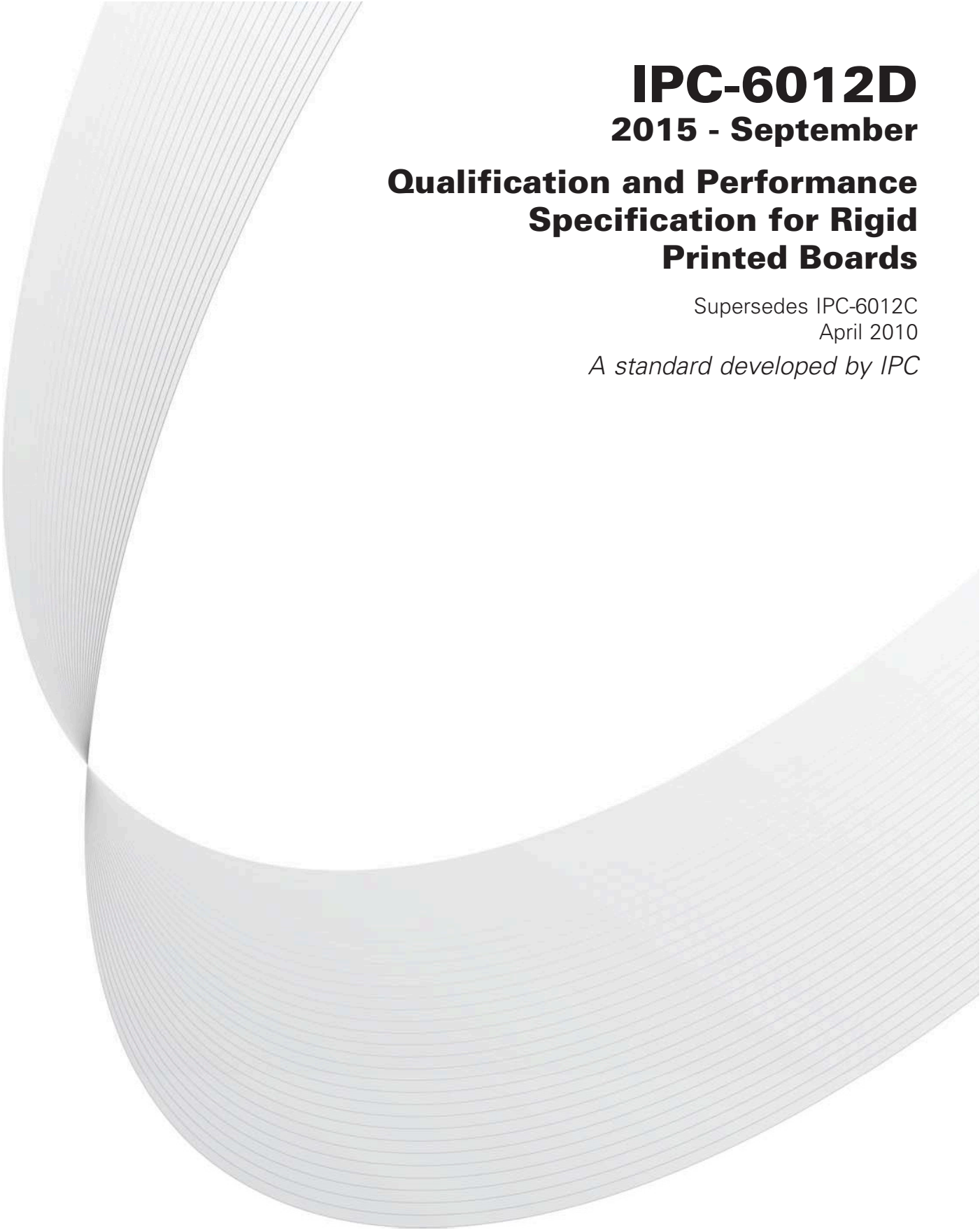
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# **IPC-6012D**

**2015 - September**

## **Qualification and Performance Specification for Rigid Printed Boards**

Supersedes IPC-6012C  
April 2010

*A standard developed by IPC*

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IPC-6012D

# Qualification and Performance Specification for Rigid Printed Boards

Developed by the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) of IPC

***Supersedes:***

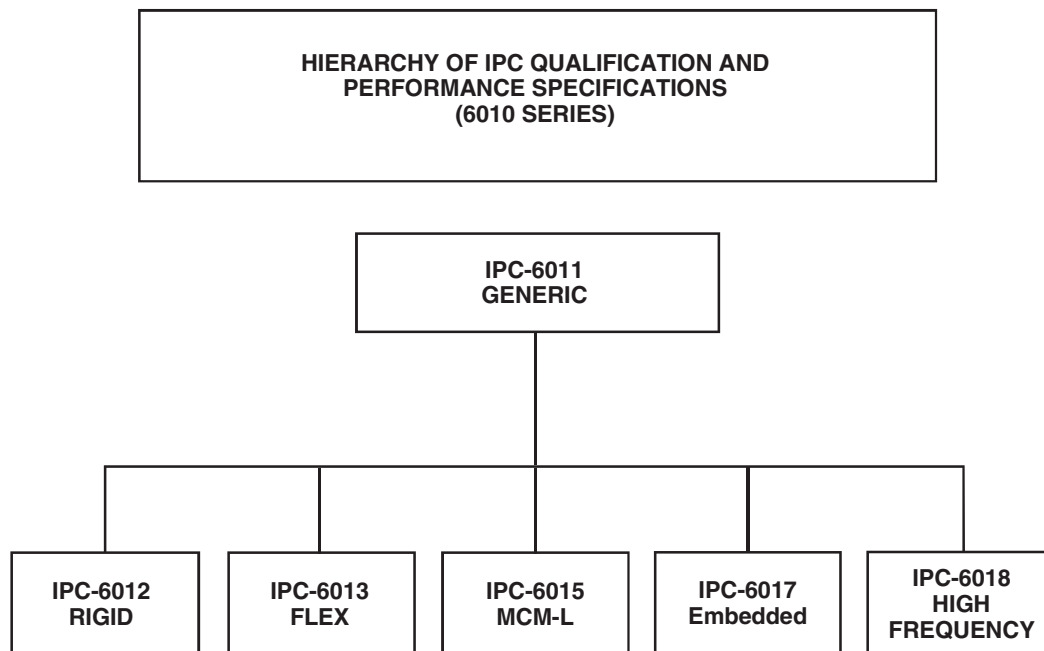
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## FOREWORD

This specification is intended to provide information on the detailed performance criteria of rigid printed boards. It supersedes IPC-6012C and was developed as a revision to those documents. The information contained herein is also intended to supplement the generic requirements identified in IPC-6011. When used together, these documents should lead both manufacturer and customer to consistent terms of acceptability.

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As technology changes, a performance specification will be updated, or new focus specifications will be added to the document set. The IPC invites input on the effectiveness of the documentation and encourages user response through completion of "Suggestions for Improvement" forms located at the end of each document.

## Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Rigid Printed Board Performance Specifications Task Group (D-33a) of the Rigid Printed Board Committee (D-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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## Table of Contents

<b>1 SCOPE</b>	1	3.2.12 Heatsink Planes, External	12
1.1 Statement of Scope	1	3.2.13 Via Protection	12
1.2 Purpose	1	3.2.14 Embedded Passive Materials	12
1.2.1 Supporting Documentation	1	3.3 Visual Examination	12
1.3 Performance Classification and Type	1	3.3.1 Edges	13
1.3.1 Classification	1	3.3.2 Laminate Imperfections	13
1.3.2 Printed Board Type	1	3.3.3 Plating and Coating Voids in the Hole	14
1.3.3 Selection for Procurement	1	3.3.4 Lifted Lands	14
1.3.4 Material, Plating Process and Final Finish	3	3.3.5 Marking	14
1.4 Terms and Definitions	4	3.3.6 Solderability	15
1.4.1 High Density Interconnects (HDI)	4	3.3.7 Plating Adhesion	15
1.4.2 Microvia	4	3.3.8 Edge Printed Board Contact, Junction of Gold Plate to Solder Finish	15
1.5 Interpretation	4	3.3.9 Workmanship	15
1.6 Presentation	4	3.4 Printed Board Dimensional Requirements	15
1.7 Revision Level Changes	4	3.4.1 Hole Size, Hole Pattern Accuracy and Pattern Feature Accuracy	16
<b>2 APPLICABLE DOCUMENTS</b>	5	3.4.2 Annular Ring and Breakout (External)	16
2.1 IPC	5	3.4.3 Bow and Twist	18
2.2 Joint Industry Standards	6	3.5 Conductor Definition	18
2.3 Federal	7	3.5.1 Conductor Width and Thickness	18
2.4 Other Publications	7	3.5.2 Conductor Spacing	18
2.4.1 American Society for Testing and Materials	7	3.5.3 Conductor Imperfections	18
2.4.2 Underwriters Lab	7	3.5.4 Conductive Surfaces	19
2.4.3 National Electrical Manufacturers Association	7	3.6 Structural Integrity	21
2.4.4 American Society for Quality	7	3.6.1 Thermal Stress Testing	21
2.4.5 AMS	7	3.6.2 Requirements for Microsectioned Coupons or Printed Boards	22
2.4.6 American Society of Mechanical Engineers	7	3.7 Solder Mask Requirements	34
<b>3 REQUIREMENTS</b>	8	3.7.1 Solder Mask Coverage	34
3.1 General	8	3.7.2 Solder Mask Cure and Adhesion	35
3.2 Materials	8	3.7.3 Solder Mask Thickness	35
3.2.1 Laminates and Bonding Material	8	3.8 Electrical Requirements	35
3.2.2 External Bonding Materials	8	3.8.1 Dielectric Withstanding Voltage	35
3.2.3 Other Dielectric Materials	8	3.8.2 Electrical Continuity and Isolation Resistance	35
3.2.4 Metal Foils	8	3.8.3 Circuit/PTH Shorts to Metal Substrate	35
3.2.5 Metal Planes/Cores	8	3.8.4 Moisture and Insulation Resistance (MIR)	35
3.2.6 Base Metallic Plating Depositions and Conductive Coatings	8	3.9 Cleanliness	36
3.2.7 Final Finish Depositions and Coatings – Metallic and Non-Metallic	9	3.9.1 Cleanliness Prior to Solder Mask Application	36
3.2.8 Polymer Coating (Solder Mask)	10	3.9.2 Cleanliness After Solder Mask, Solder, or Alternative Surface Coating Application	36
3.2.9 Fusing Fluids and Fluxes	10	3.9.3 Cleanliness of Inner Layers After Oxide Treatment Prior to Lamination	36
3.2.10 Marking Inks	10		
3.2.11 Hole Fill Insulation Material	12		



3.10	Special Requirements .....	36	Figure 3-8	Plated Hole Microsection (Grinding/ Polishing) Tolerance .....	22
3.10.1	Outgassing .....	36	Figure 3-9	An Example of Plating to Target Land Separation .....	22
3.10.2	Fungus Resistance .....	36	Figure 3-10	Crack Definition .....	24
3.10.3	Vibration .....	36	Figure 3-11	Separations at External Foil .....	24
3.10.4	Mechanical Shock .....	36	Figure 3-12	Plating Folds/Inclusions – Minimum Measurement Points .....	24
3.10.5	Impedance Testing .....	37	Figure 3-13	Microsection Evaluation Laminate Attributes .....	25
3.10.6	Coefficient of Thermal Expansion (CTE) .....	37	Figure 3-14	Measurement for Etchback .....	25
3.10.7	Thermal Shock .....	37	Figure 3-15	Measurement for Dielectric Removal .....	26
3.10.8	Surface Insulation Resistance (As Received) .....	37	Figure 3-16	Measurement for Negative Etchback .....	26
3.10.9	Metal Core (Horizontal Microsection) .....	37	Figure 3-17	Annular Ring Measurement (Internal) .....	27
3.10.10	Rework Simulation .....	37	Figure 3-18	Microsection Rotations for Breakout Detection .....	27
3.10.11	Bond Strength, Unsupported Component Hole Land .....	37	Figure 3-19	Comparison of Microsection Rotations .....	27
3.10.12	Destructive Physical Analysis .....	37	Figure 3-20	Example of Non-Conforming Dielectric Spacing Reduction Due to Breakout at Microvia Target Land .....	28
3.10.13	Peel Strength Requirements (For Foil Laminated Construction Only) .....	37	Figure 3-21	Surface Copper Wrap Measurement for Filled Holes .....	28
3.11	Repair .....	38	Figure 3-22	Surface Copper Wrap Measurement for Non-Filled Holes .....	28
3.11.1	Circuit Repairs .....	38	Figure 3-23	Wrap Copper in Type 4 Printed Board (Acceptable) .....	29
3.12	Rework .....	38	Figure 3-24	Wrap Copper Removed by Excessive Sanding/Planarization/Etching (Not Acceptable) .....	29
<b>4</b>	<b>QUALITY ASSURANCE PROVISIONS</b> .....	38	Figure 3-25	Copper Cap Thickness .....	30
4.1	General .....	38	Figure 3-26	Copper Cap Filled Via Height (Bump) .....	30
4.1.1	Qualification .....	38	Figure 3-27	Copper Cap Depression (Dimple) .....	30
4.1.2	Sample Test Coupons .....	38	Figure 3-28	Copper Cap Plating Voids .....	30
4.2	Acceptance Tests .....	38	Figure 3-29	Example of Acceptable Voiding in a Cap Plated, Copper Filled Microvia .....	31
4.2.1	C=0 Zero Acceptance Number Sampling Plan .....	38	Figure 3-30	Example of Acceptable Voiding in a Copper Filled Microvia without Cap Plating .....	31
4.2.2	Referee Tests .....	39	Figure 3-31	Example of Nonconforming Void in a Cap Plated, Copper Filled Microvia .....	31
4.3	Quality Conformance Testing .....	39	Figure 3-32	Example of Nonconforming Void in a Copper Filled Microvia .....	31
4.3.1	Coupon Selection .....	39	Figure 3-33	Microvia Contact Dimension .....	31
<b>5</b>	<b>NOTES</b> .....	44	Figure 3-34	Exclusion of Separations in Microvia Target Land Contact Dimension .....	32
5.1	Ordering Data .....	44	Figure 3-35	Penetration of Microvia Target Land .....	32
5.2	Superseded Specifications .....	44	Figure 3-36	Metal Core to PTH Spacing .....	33
<b>APPENDIX A</b>	.....	45	Figure 3-37	Measurement of Minimum Dielectric Spacing .....	33
			Figure 3-38	Fill Material in Blind/Through Vias When Cap Plating Not Specified .....	34
	<b>Figures</b>				
Figure 1-1	Microvia Definition .....	4			
Figure 3-1	Annular Ring Measurement (External) .....	17			
Figure 3-2	Breakout of 90° and 180° .....	18			
Figure 3-3	External Conductor Width Reduction .....	18			
Figure 3-4	Example of Intermediate Target Land in a Microvia .....	18			
Figure 3-5	Rectangular Surface Mount Lands .....	19			
Figure 3-6	Round Surface Mount Lands .....	19			
Figure 3-7	Printed Board Edge Connector Lands .....	20			

### Tables

Table 1-1	Technology Adders .....	2
Table 1-2	Default Requirements .....	3
Table 3-1	Metal Planes/Cores .....	8
Table 3-2	Maximum Limits of SnPb Solder Bath Contaminant .....	9
Table 3-3	Final Finish and Coating Requirements .....	11
Table 3-4	Surface and Hole Copper Plating Minimum Requirements for Buried Vias > 2 Layers, Through-Holes, and Blind Vias .....	12
Table 3-5	Surface and Hole Copper Plating Minimum Requirements for Microvias (Blind and Buried) .....	12
Table 3-6	Surface and Hole Copper Plating Minimum Requirements for Buried Cores (2 layers) .....	12
Table 3-7	Plating and Coating Voids in the Hole .....	14
Table 3-8	Edge Printed Board Contact Gap .....	15
Table 3-9	Minimum Annular Ring .....	17
Table 3-10	Plated Hole Integrity After Stress .....	23
Table 3-11	Cap Plating Requirements for Filled Holes .....	30
Table 3-12	Microvia Contact Dimension .....	31
Table 3-13	Internal Layer Foil Thickness after Processing .....	32
Table 3-14	External Conductor Thickness after Plating .....	33
Table 3-15	Solder Mask Adhesion .....	35
Table 3-16	Dielectric Withstanding Voltages .....	35
Table 3-17	Insulation Resistance .....	36
Table 4-1	Qualification Test Coupons .....	39
Table 4-2	C=0 Sampling Plan per Lot Size .....	40
Table 4-3	Acceptance Testing and Frequency .....	40
Table 4-4	Quality Conformance Testing .....	44